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Facsimile

Date:

May 19, 2003

Deliver To:

John Vigushin (GAU 2827)

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Re:

Serial No. 10/002,732 (docket no. P012-1)

From:

David M. Sigmond

The following documents are attached:

1. Second Preliminary Amendment (5 pages)

2. Markstein et al. (6 pages) (Ref AP, PTO-1449, p1)

3. Elenius (3 pages) (Ref AQ, PTO-1449, p1)

4. Erickson (3 pages) (Ref AP, PTO-1449, p2)

5. Kuchenmeister et al. (5 pages) (Ref AQ, PTO-1449, p2)

6. Ghaffarian (4 pages) (Ref AP, PTO-1449, p3)

Please note the references are complete (and identical to the original submissions). The skipped pages are advertisements.

Please let me know if I can assist further.

TOTAL NUMBER OF PAGES: 27 (Including This Page)

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Charles W.C. Lin

Title:

SUPPORT CIRCUIT WITH A TAPERED THROUGH-HOLE

FOR A SEMICONDUCTOR CHIP ASSEMBLY

Serial No.:

10/002,732

Filed:

November 15, 2001

Examiner:

Vigushin, J.

Group Art Unit:

2827

Atty. Docket No.:

P012-1

COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, VA 22313-1450

SECOND PRELIMINARY AMENDMENT

Dear Sir:

Please amend the application as follows.

In the Abstract

Replace the paragraph at page 35, lines 1-19 with the following paragraph:

A support circuit is adapted to be mechanically and electrically coupled to a semiconductor chip such that the support circuit and the chip in combination form a semiconductor chip assembly. The support circuit includes an insulative base and a conductive trace embedded in the insulative base. The conductive trace is a single continuous piece of metal, the conductive trace includes a pillar that extends above the insulative base and a routing line that is substantially covered by and extends below the insulative base, and an opening in the routing line has tapered sidewalls and a diameter that increases as height increases.